

#8/Assoc/A
Q700
PATENT
10/31/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Kinsman et al.

Serial No.: 09/917,127

Filed: July 27, 2001

For: METHOD FOR FABRICATING A
CHIP SCALE PACKAGE USING WAFER
LEVEL PROCESSING AND DEVICES
RESULTING THEREFROM

Confirmation No.: 3326

Examiner: M. Trinh

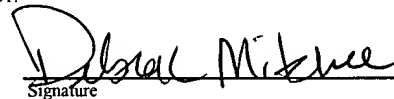
Group Art Unit: 2822

Attorney Docket No.: 2269-3572.1US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

October 18, 2002
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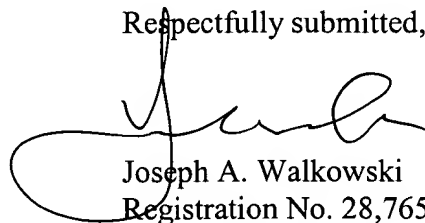
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Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. § 1.34(b), please recognize the following individual as an associate agent/attorney herein in connection with the above-identified patent application, and with all continuing and divisional applications hereof:

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Respectfully submitted,



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